

BFP540FESD

Low profile robust silicon NPN RF bipolar transistor



Product description

The BFP540FESD is a low noise device based on a grounded emitter (SIEGET™) that is part of Infineon’s established fifth generation RF bipolar transistor family. Its high gain and ESD structure make the device suitable for applications that requires highly robustness and high performance. It remains cost competitive without compromising on ease of use.



Feature list

- Minimum noise figure $NF_{min} = 0.9$ dB at 1.8 GHz, 2 V, 5 mA
- High gain $G_{ms} = 20$ dB at 1.8 GHz, 2 V, 20 mA
- $OIP_3 = 24.5$ dBm at 1.8 GHz, 2 V, 20 mA
- High ESD robustness, typical 1 kV (HBM)

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

- Radio-frequency oscillators such as local oscillator in LNB
- Broadband low noise amplifiers (LNAs) for CATV, DVB-T, DAB/DMB and FM/AM radio
- LNAs for wireless communications such as cordless phones

Device information

Table 1 Part information

Product name / Ordering code	Package	Pin configuration				Marking	Pieces / Reel
BFP540FESD / BFP540FESDH6327XTSA1	TSFP-4-1	1 = B	2 = E	3 = C	4 = E	AUs	3000

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions

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Absolute maximum ratings

1 Absolute maximum ratings

Table 2 Absolute maximum ratings at $T_A = 25\text{ °C}$ (unless otherwise specified)

Parameter	Symbol	Values		Unit	Note or test condition	
		Min.	Max.			
Collector emitter voltage	V_{CEO}	-	4.5	V	Open base	
			4		$T_A = -55\text{ °C}$, open base	
Collector emitter voltage	V_{CES}		10		E-B short circuited	
Collector base voltage	V_{CBO}		10		Open emitter	
Emitter base voltage	V_{EBO}		1		Open collector	
Base current	I_B		8		mA	-
Collector current	I_C		80			
Total power dissipation ¹⁾	P_{tot}		250	mW	$T_S \leq 80\text{ °C}$	
Junction temperature	T_J		150	°C	-	
Storage temperature	T_{Stg}	-55				

Attention: *Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit.*

¹ T_S is the soldering point temperature. T_S is measured on the emitter lead at the soldering point of the PCB.

Thermal characteristics

2 Thermal characteristics

Table 3 Thermal resistance

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Junction - soldering point	R_{thJS}	-	280	-	K/W	-

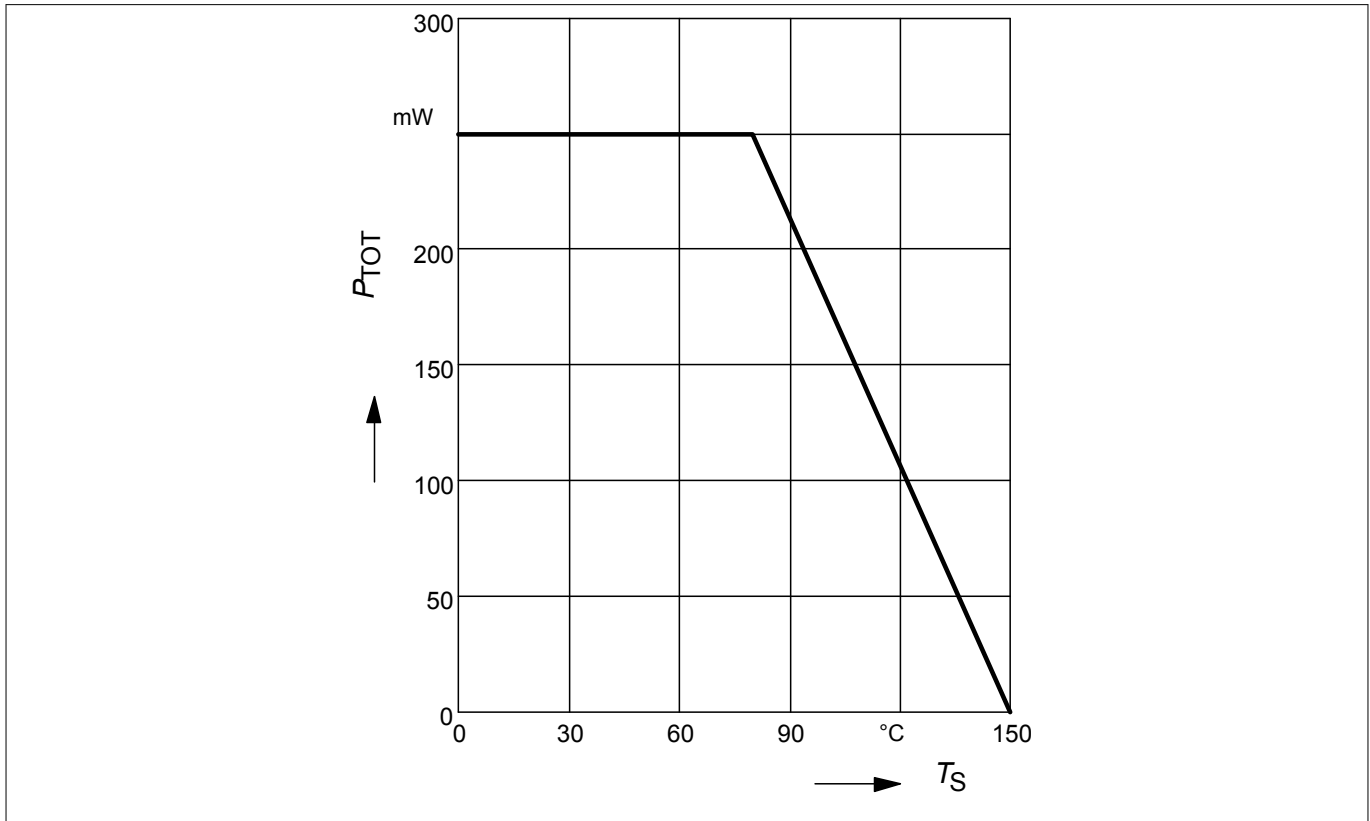


Figure 1 Total power dissipation $P_{tot} = f(T_s)$

Electrical characteristics

3 Electrical characteristics

3.1 DC characteristics

Table 4 DC characteristics at $T_A = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Collector emitter breakdown voltage	$V_{(BR)CEO}$	4.5	5	–	V	$I_C = 1\text{ mA}$, $I_B = 0$, open base
Collector emitter leakage current	I_{CES}	–	–	10 ²⁾	μA	$V_{CE} = 10\text{ V}$, $V_{BE} = 0$, E-B short circuited
Collector base leakage current	I_{CBO}			100 ²⁾	nA	$V_{CB} = 5\text{ V}$, $I_E = 0$, open emitter
Emitter base leakage current	I_{EBO}			10 ²⁾	μA	$V_{EB} = 0.5\text{ V}$, $I_C = 0$, open collector
DC current gain	h_{FE}	50	110	170		$V_{CE} = 3.5\text{ V}$, $I_C = 20\text{ mA}$, pulse measured

3.2 General AC characteristics

Table 5 General AC characteristics at $T_A = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Transition frequency	f_T	21	30	–	GHz	$V_{CE} = 4\text{ V}$, $I_C = 50\text{ mA}$, $f = 1\text{ GHz}$
Collector base capacitance	C_{CB}	–	0.16	0.26	pF	$V_{CB} = 2\text{ V}$, $V_{BE} = 0$, $f = 1\text{ MHz}$, emitter grounded
Collector emitter capacitance	C_{CE}		0.4	–		$V_{CE} = 2\text{ V}$, $V_{BE} = 0$, $f = 1\text{ MHz}$, base grounded
Emitter base capacitance	C_{EB}		0.55			$V_{EB} = 0.5\text{ V}$, $V_{CB} = 0$, $f = 1\text{ MHz}$, collector grounded

² Maximum values not limited by the device but by the short cycle time of the 100% test.

Electrical characteristics

3.3 Frequency dependent AC characteristics

Measurement setup is a test fixture with Bias-T's in a 50 Ω system, $T_A = 25\text{ °C}$.

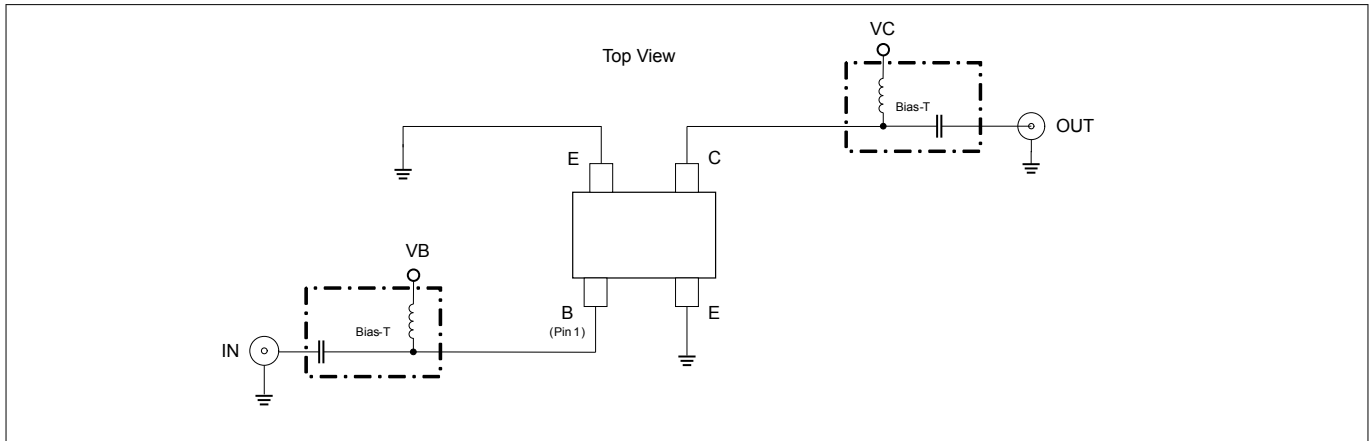


Figure 2 Testing circuit

Table 6 AC characteristics, $V_{CE} = 2\text{ V}$, $f = 1.8\text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	$I_C = 20\text{ mA}$
<ul style="list-style-type: none"> Maximum stable power gain Transducer gain 	G_{ms} $ S_{21} ^2$	– 15.5	20 18	–		
Noise figure					dBm	$I_C = 5\text{ mA}$
<ul style="list-style-type: none"> Minimum noise figure 	NF_{min}	–	0.9	1.4		
Linearity					dBm	$I_C = 20\text{ mA}$, $Z_S = Z_L = 50\text{ }\Omega$
<ul style="list-style-type: none"> 3rd order intercept point at output 1 dB gain compression point at output 	OIP_3 OP_{1dB}		24.5 11	–		

Table 7 AC characteristics, $V_{CE} = 2\text{ V}$, $f = 3\text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	$I_C = 20\text{ mA}$
<ul style="list-style-type: none"> Maximum available power gain Transducer gain 	G_{ma} $ S_{21} ^2$	–	14.5 13	–		
Noise figure					dBm	$I_C = 5\text{ mA}$
<ul style="list-style-type: none"> Minimum noise figure 	NF_{min}		1.3			

Note: $G_{ms} = |S_{21}/S_{12}|$ for $k < 1$; $G_{ma} = |S_{21}/S_{12}|(k - (k^2 - 1)^{1/2})$ for $k > 1$. In order to get the NF_{min} values stated in this chapter, the test fixture losses have been subtracted from all measured results. OIP_3 value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50 Ω from 0.1 MHz to 6 GHz.

Package information TSFP-4-1

4 Package information TSFP-4-1

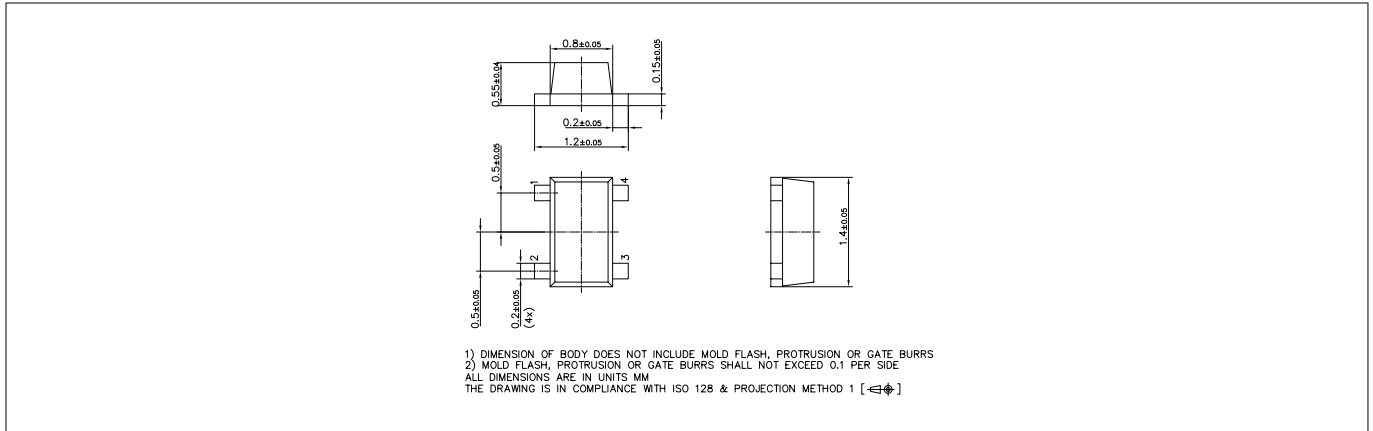


Figure 3 Package outline

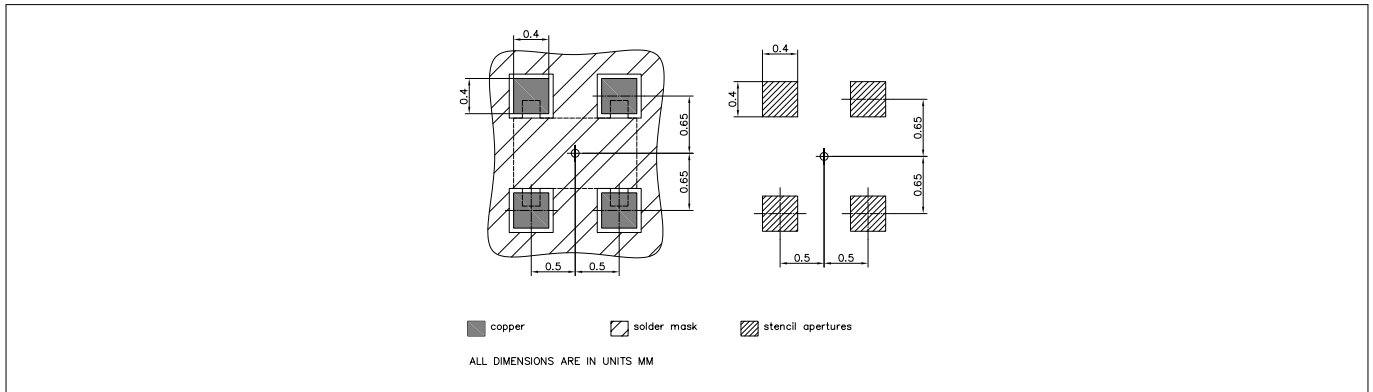


Figure 4 Foot print

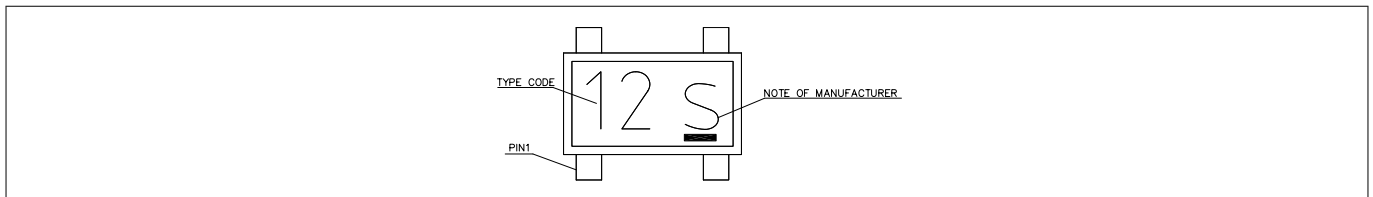


Figure 5 Marking layout example

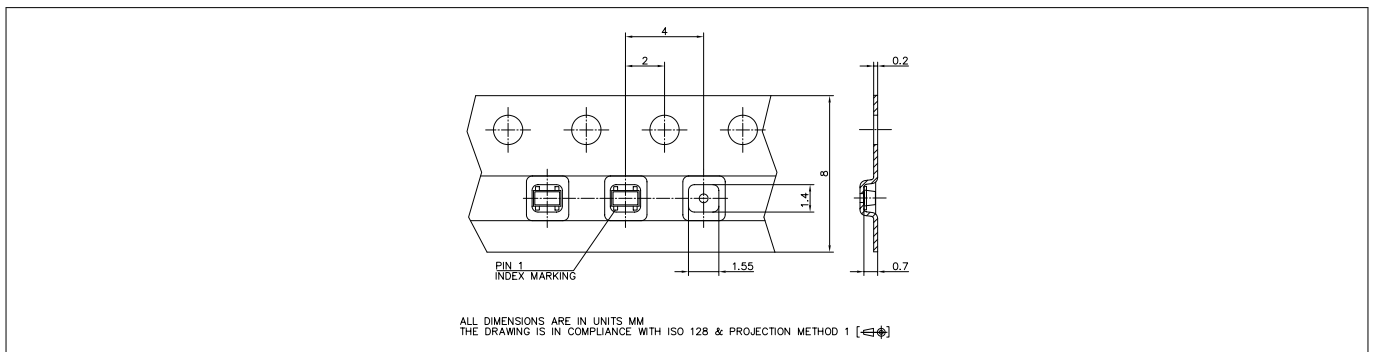


Figure 6 Tape dimensions

Revision history

Revision history

Document version	Date of release	Description of changes
Revision 2.0	2019-01-25	New datasheet layout.

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Edition 2019-01-25

**Published by
Infineon Technologies AG
81726 Munich, Germany**

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**Document reference
IFX-pcg1525441545262**

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